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May 2015

FSV1045V 10 A, 45 V Ultra-Low VF Schottky Rectifier

Features

- Ultra-Low Forward Voltage Drop:
 - 0.41 V Typical at 10 A, T_A = 25°C
 - 0.44 V Maximum at 10 A, $T_A = 25$ °C
- Low Thermal Resistance
- Very Low Profile: Typical Height of 1.1 mm
- RoHS Compliant
- Halogen Free
- Meets MSL 1 per JESD22-A111 Full-Body Solder Immersion

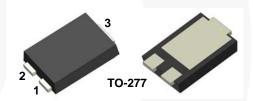
Applications

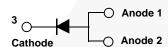
- Mobile Charger
- Solar Panel
- · Reverse Polarity Protection

Description

The FSV1045V schottky rectifier offers break-through size and performance. The device is optimized for mobile charger applications. It sinks only 18 mA reverse current at high temperature and provides forward voltage drop of 0.18 V at 1 A operating current in a charger design.

All this capability is packed into a small, flat-lead, TO-277 package, optimized for space-constrained applications. The FSV1045V supports a typical Z height of 1.1 mm. It is RoHS compliant and halogen free. It is also qualified for a wave soldering process.





Ordering Information

Part Number	Top Mark	Package	Packing Method
FSV1045V	FSV1045V	TO-277 3L	Tape and Reel

Absolute Maximum Ratings(1)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at $T_A = 25^{\circ}\text{C}$ unless otherwise noted.

Symbol	Parameter	Value	Unit
V _{RRM}	Peak Repetitive Reverse Voltage	45	V
V _{RWM}	Working Peak Reverse Voltage	45	V
V _{RMS}	RMS Reverse Voltage	32	V
V _R	DC Blocking Voltage	45	V
Io	Average Rectified Output Current ⁽²⁾ T _L = 105°C	10	Α
I _{FSM}	Non-Repetitive Peak Forward Surge Current (3)	300	Α
CJ	Typical Junction Capacitance $V_R = 4 V$, 1 MHz	820	pF
T _J	Operating Junction Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

Notes:

- 1. All tests conducted at $T_A = T_J = 25$ °C unless otherwise noted.
- 2. Mounted on 30 mm x 30 mm FR4 PCB.
- 3. Pulse condition: 8.3 ms single half-sine wave. Test method is compliant with MIL standard. (MIL-STD-750E)

Thermal Characteristics(4)

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Minimum Land Pattern	Maximum Land Pattern	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance		40	°C/W
ΨJL	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Anode	15	12	°C/W
	Junction-to-Lead Thermal Characteristics, Thermocouple Soldered to Cathode	6	5	C/VV

Note

4. The thermal resistances ($R_{\theta JA} \& \psi_{JL}$) are characterized with device mounted on the following FR4 printed circuit boards, as shown in Figure 1 and Figure 2. PCB size: 76.2 x 114.3 mm. Minimum land pattern size: 4.9 x 4.8 mm (big pattern, x1), 1.4 x 1.52 mm (small pattern, x2). Maximum land pattern size: 30 x 30 mm (pattern, x2). Force line trace size = 55 mils, sense line trace size = 4 mils.



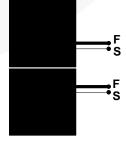


Figure 1. Minimum Land Pattern of 2 oz Copper

Figure 2. Maximum Land Pattern of 2 oz Copper

Electrical Characteristics

Values are at $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions		Min.	Тур.	Max.	Unit
V _{BR}	Breakdown Voltage	I _T = 500 μA		45			V
V _F Forward \	Forward Voltage Drop	I _F = 1 A	T _A = 25°C		0.28		V
		I _F = 10 A			0.41	0.44	
		I _F = 1 A	T _A = 125°C		0.18		
		I _F = 10 A			0.36	0.39	
I _R	Maximum Leakage	V – V	T _A = 25°C		0.065	0.220	- mA
		$V = V_{RWM}$	T _A = 125°C		19	32	

Typical Performance Characteristics

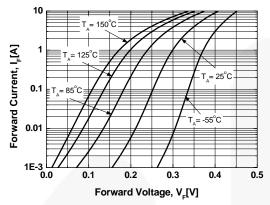
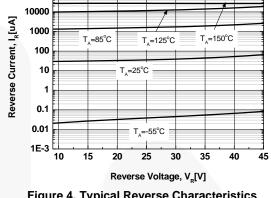


Figure 3. Forward Current Characteristics



100000

Figure 4. Typical Reverse Characteristics

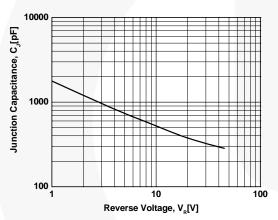


Figure 5. Typical Junction Capacitance

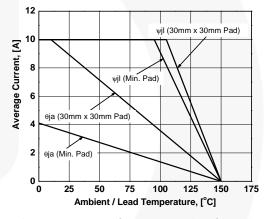


Figure 6. Forward Current Derating Curve

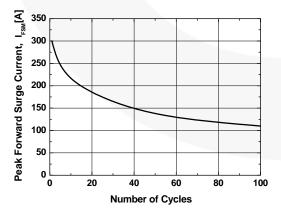
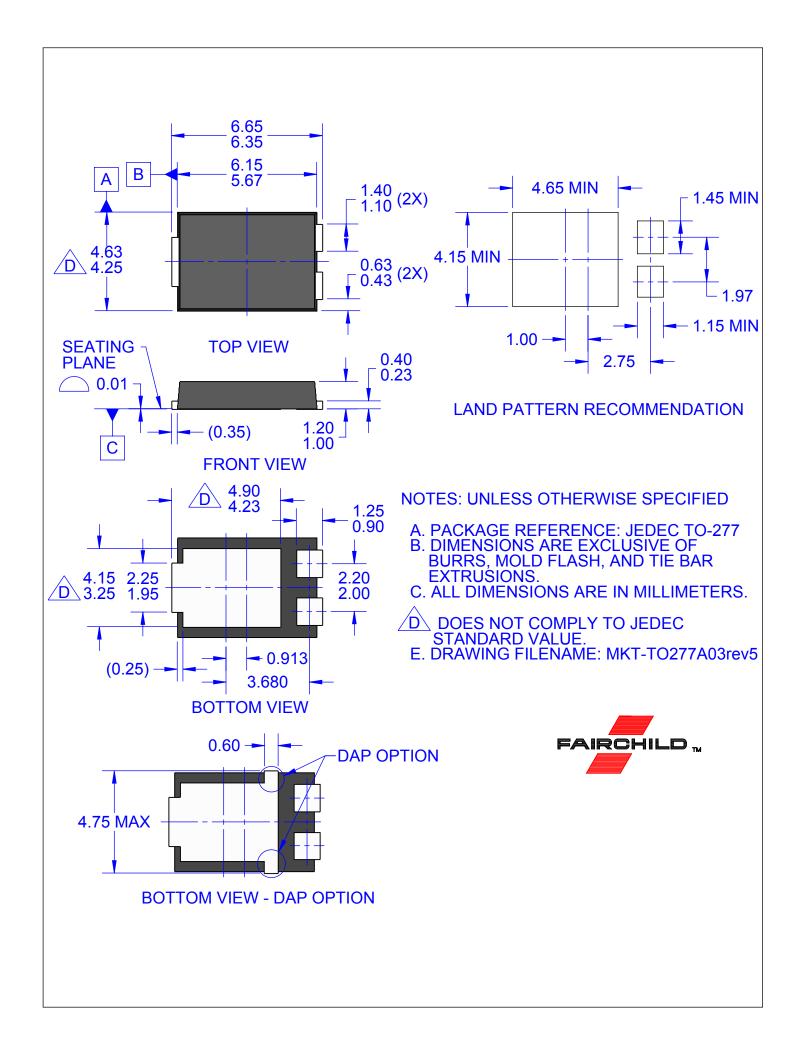


Figure 7. Surge Current Derating Curve



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